



# DZ2703000L

Silicon epitaxial planar type

For constant voltage / For surge absorption circuit  
 DZ2S030 in SSSMini2 type package

■ Features

- Excellent rising characteristics of zener current I<sub>Z</sub>
- Low zener operating resistance R<sub>Z</sub>
- Halogen-free / RoHS compliant  
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: 3J

■ Packaging

Embossed type (Thermo-compression sealing) 10 000 pcs / reel (standard)

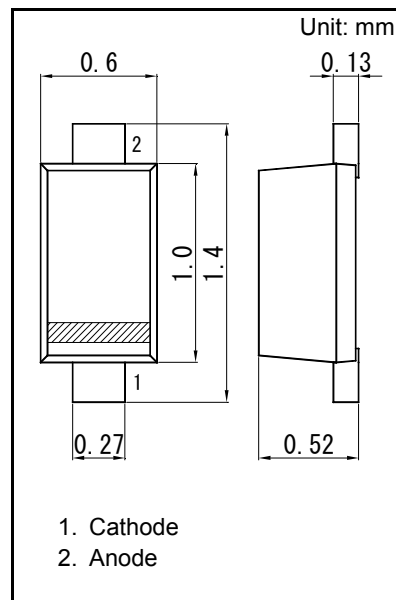
■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	IFRM	200	mA
Total power dissipation <sup>*1</sup>	PT	120	mW
Electrostatic discharge <sup>*2</sup>	ESD	±15	kV
Junction temperature	T <sub>j</sub>	150	°C
Operating ambient temperature	T <sub>opr</sub>	-40 to +85	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

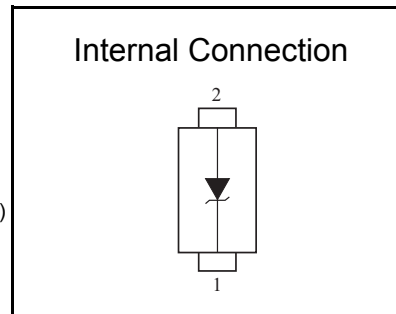
Note) \*1: Mounted on glass epoxy print board. ( 45 mm x 45 mm x 1 mm)

Solder in ( 0.4 mm x 0.3 mm)

\*2: Test method: IEC61000\_4\_2(C = 150 pF, R = 330 Ω, Contact discharge: 10 times)



Panasonic	SSSMini2-F4-B
JEITA	SC-104A
Code	SOD-723



■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 10 mA			1.0	V
Zener voltage <sup>*1, *2</sup>	V <sub>Z</sub>	I <sub>Z</sub> = 5 mA	2.85		3.15	V
Zener operating resistance	R <sub>Z</sub>	I <sub>Z</sub> = 5 mA			120	Ω
Reverse current	I <sub>R</sub>	V <sub>R</sub> = 1.0 V			50	μA
Temperature coefficient of zener voltage <sup>*3</sup>	SZ	I <sub>Z</sub> = 5 mA		-2.0		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. Absolute frequency of input and output is 5 MHz.

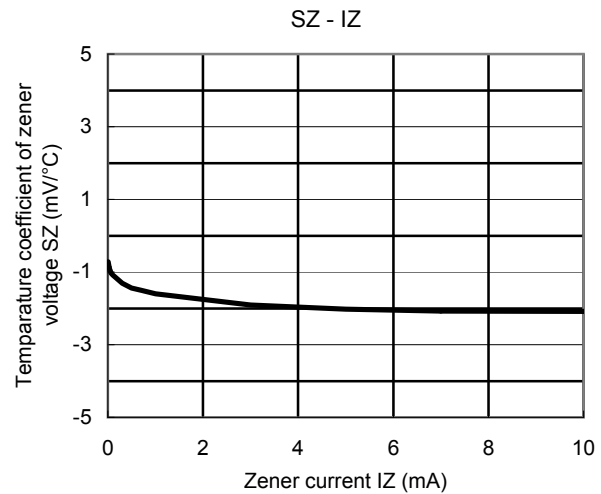
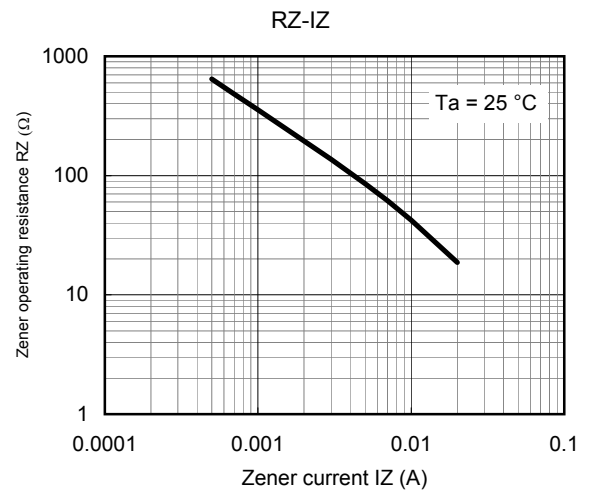
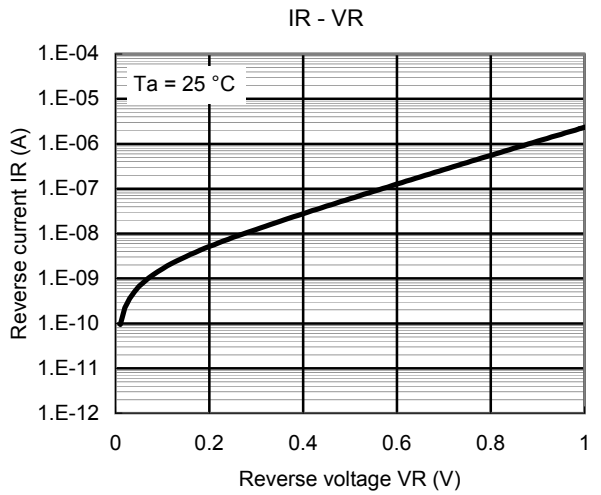
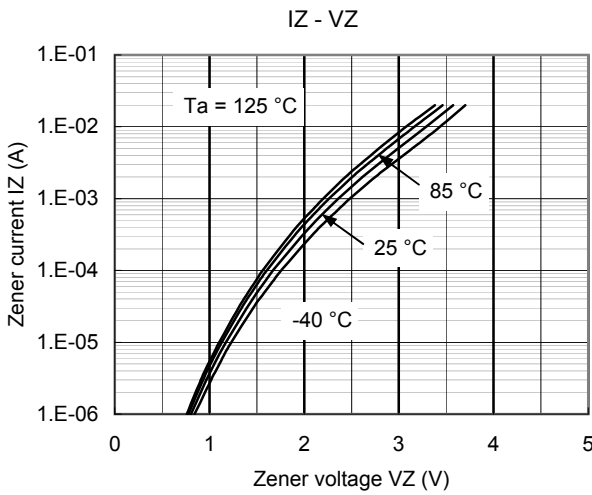
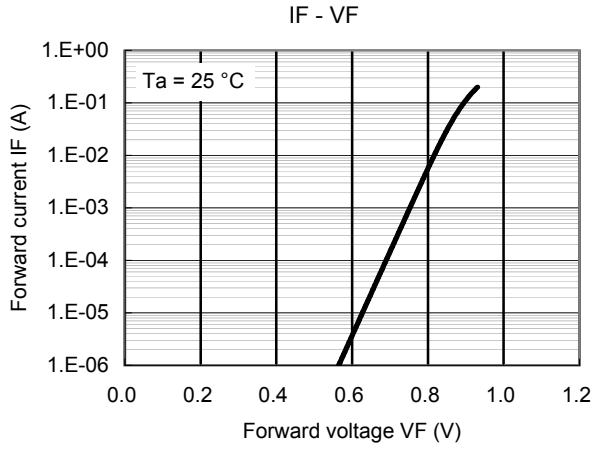
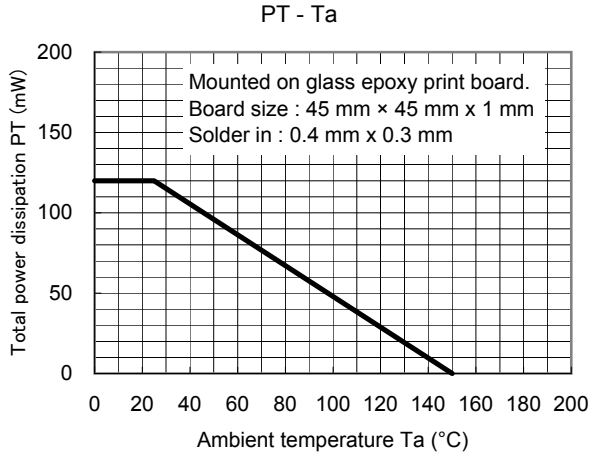
3. \*1 The temperature must be controlled 25 °C for V<sub>Z</sub> measurement.

V<sub>Z</sub> value measured at other temperature must be adjusted to V<sub>Z</sub> (25 °C)

\*2 V<sub>Z</sub> guaranteed 20 ms after current flow.

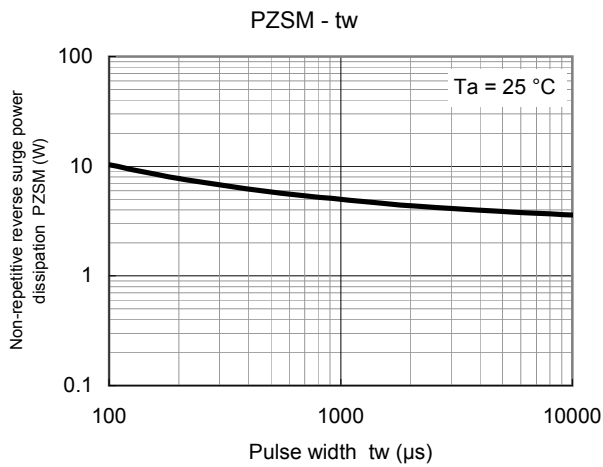
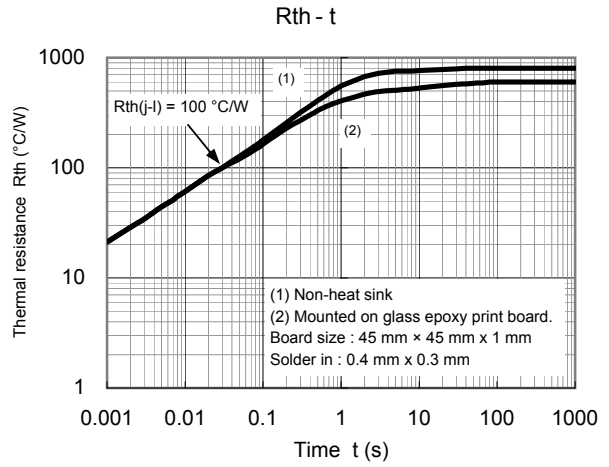
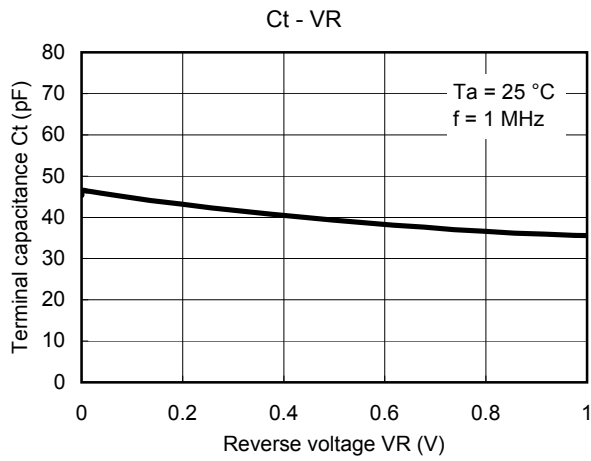
\*3 T<sub>j</sub> = 25 °C to 150 °C

Technical Data ( reference )



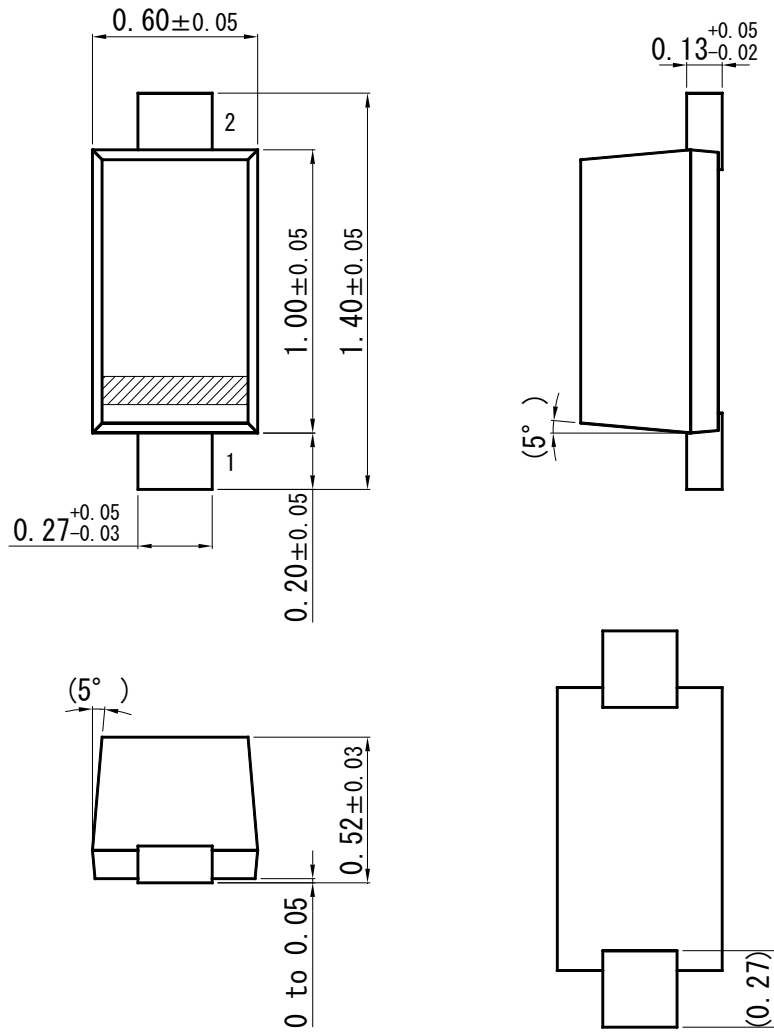


Technical Data ( reference )

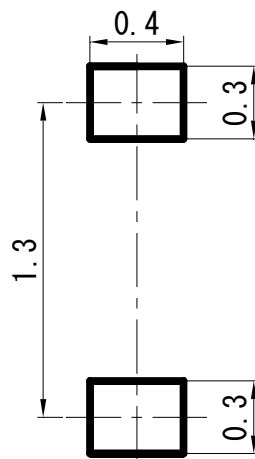


SSSMini2-F4-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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